

C0603C104M3RACTU

Aliases (C0603C104M3RAC7867)

SMD Comm X7R, Ceramic, 0.1 uF, 20%, 25 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0603



Click here for the 3D model.

| Dimensions | |
|------------|------------------|
| Chip Size | 0603 |
| L | 1.6mm +/-0.15mm |
| W | 0.8mm +/-0.15mm |
| т | 0.8mm +/-0.15mm |
| S | 0.7mm MIN |
| В | 0.35mm +/-0.15mm |

Гаре

| Packaging Specifications | |
|--------------------------|---------------------|
| Packaging | T&R, 180mm, Paper T |
| Packaging Quantity | 4000 |

| General Information | |
|---------------------|---|
| Series | SMD Comm X7R |
| Style | SMD Chip |
| Description | SMD, MLCC, Temperature Stable, Class II |
| Features | Temperature Stable, Class II |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 7.3 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|---|--|
| Capacitance | 0.1 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 20% |
| Voltage DC | 25 VDC |
| Dielectric Withstanding Voltage | 62.5 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 3.5%1kHz1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 48 Hours |
| Insulation Resistance | 5 GOhms |

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